

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ISAO OCHIAI	12/17/2002
KAZUMI ONDA	12/17/2002
RECEIVING PARTY DATA	
Name:	SANYO ELECTRIC CO., LTD.
Street Address:	2-5-5, KEIHANHONDORI
City:	MORIGUCHI-CITY, OSAKA
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	10772345
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NAME OF SUBMITTER:	KELLY A NELSON
SIGNATURE:	/Kelly A Nelson/
DATE SIGNED:	01/23/2015
Total Attachments: 1	
source=200105590 Assignment F1020584#page1.tif	

ASSIGNMENT

WHEREAS, We, 1) **Isao Ochiai**, a citizen of Japan, residing at 11-14, Kumano-cho, Ota-city, Gunma, Japan and 2) **Kazumi Onda**, residing at 2624 Mitakaya, hanyu-city, Saitama, Japan (hereinafter Assignors) are the inventors of an invention in LEAD FRAME, RESIN SEALING MOLD, AND METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE USING THE SAME for which we filed a U.S. Patent Application on November 12, 2002 having Serial Number 10/291,815; and

WHEREAS, **Sanyo Electric Co., Ltd.**, with a place of business at 2-5-5, Keihanhondori, Moriguchi-city, Osaka, Japan (hereinafter Assignee), is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we, the said Assignors have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said Assignee, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may hereafter be filed for said invention in any country or countries foreign to the United States, and all Letters Patent which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof and all rights of priority in any such country or countries based upon the filing of the said application for Letters Patent of the United States which are created by any law, treaty or international convention; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said Assignee, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said Assignee, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN TESTIMONY WHEREOF, we hereunto set our hand and seal the date(s) identified below.

Isao Ochiai
ISAO OCHIAI

DATE

Dec / 17 / 2002

KAZUMI ONDA
KAZUMI ONDA

DATE

Dec. / 17 / 2002